

49 7x7 FBGA, RoHS compliant, Package Weight

Device name: VS1002D-B/LSR-RoHS

Document: A

Component	Weight (g)	Type	Material	%	Weight (g)
Chip	0.0165		Customer die	100.00	1.65E-02
Substrate	0.0026	49FBGA 7x7x1.45mm	R0049ST-05A (1E04971)	100.00	2.64E-03
Mold Compound	0.0890	SUMIKON EMEG760V	Fused Silica	95.00	8.46E-02
			Epoxy Resin	2.00	1.78E-03
			Phenol Resin	0.50	4.45E-04
			Antimony Trioxide	1.00	8.90E-04
			Brominated Epoxy Resin	1.00	8.90E-04
			Carbon Black	0.50	4.45E-04
Bonding Wires	0.00104	25μ NL51, 53 wires (1 wire ave weight ~1.968E-05gram)	Au	99.990	1.04E-03
			Ag	0.0008	8.34E-09
			Be	0.0010	1.04E-08
			Ca	0.0032	3.34E-08
			Cu	0.0005	5.22E-09
			Fe	0.0005	5.22E-09
			Mg	0.0005	5.22E-09
Epoxy	0.0060	Ablebond 2000B	Silver (Ag)	70.00	4.20E-03
			Epoxy Resin	5.00	3.00E-04
			Diester	10.00	6.00E-04
			Polymeric Resin	5.00	3.00E-04
			Functionalized Ester	10.00	6.00E-04
Solder Balls	0.0169	96.5Sn, 3Ag, 0.5Cu / 18 mils (1 solder ball ave wt ~3.4467E-04 gram)	Tin (Sn)	96.50	1.63E-02
			Silver (Ag)	3.00	5.07E-04
			Copper (Cu)	0.50	8.45E-05
Total Weight	0.1320 gram				0.1320 gram

\* Chemical Percent composition for epoxy, Au wires, mold compound & Solder balls are from supplier TDS & MSDS.